

04-06-1998

AS

FORM COVER SHEET *Patents Only*

To the Honorable Commissioner,

100673658

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March 17, 1998

Attorney Dkt: 5649.400

Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chang-seok Kang

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.  
416 Maetan-dong  
Paldal-gu, Suwon-City  
Kyungki-do  
Republic of Korea

Additional name(s) of conveying party(ies) attached? \_\_\_ Yes X No

3. Nature of conveyance:

X \_\_\_ Assignment  
\_\_\_ Merger  
\_\_\_ Security Agreement  
\_\_\_ Change of Name  
\_\_\_ Other \_\_\_\_\_

Execution Date: October 15, 1997

Additional name(s) & address(es) attached? \_\_\_ Yes X NoApplication Serial No. 08/947,946, filed October 9, 1997 Patent No.

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

Additional numbers attached? \_\_\_ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

Mitchell S. Bigel, Esq.  
**Myers Bigel Sibley & Sajovec**  
P. O. Box 37428  
Raleigh NC 27627

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00  
X \_\_\_ Enclosed  
\_\_\_ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Scott C. Hatfield, Reg. No. 38,176

Name of Person Signing

Signature

March 17, 1998

Date

Total number of pages including cover sheet, attachments and document: 300000112 08947946 40.00 IP  
04/07/1998 TT0411  
01 FC:561PATENT  
REEL: 9059 FRAME: 0343

**ASSIGNMENT**

THIS ASSIGNMENT, made by me, **Chang-seok Kang**, a citizen of the Republic of Korea, residing at 103-904, Hyundai Apt., 810-1, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea;

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **METHODS OF FORMING INTEGRATED CIRCUIT CAPACITORS INCLUDING ETCH STOPPING LAYERS** for which an application for United States Letters Patent has been filed in the United States Patent and Trademark Office. I hereby authorize and request Myers, Bigel, Sibley & Sajovec, L.L.P., to insert here in parentheses (Application No. 08/947,946, filed October 9, 1997) the filing date and application number of said application when known, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-City, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to bind my heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this  
15th day of October, 1997.

  
Chang-seok Kang

Witnessed by:

\_\_\_\_\_

Date: \_\_\_\_\_

\_\_\_\_\_

Date: \_\_\_\_\_